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(12) **United States Design Patent** (10) **Patent No.:** **US D796,458 S**
Jang et al. (45) **Date of Patent:** **** Sep. 5, 2017**

(54) **GAS FLOW CONTROL PLATE FOR SEMICONDUCTOR MANUFACTURING APPARATUS**

21/6708; H01L 21/68098; H01L 21/67109; H01L 21/68714; F27B 15/00; F27B 15/006; F27B 15/10; F27D 5/0037; F27D 5/02; F27D 5/00; F27D 5/023

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See application file for complete search history.

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(**) Term: **15 Years**

(74) *Attorney, Agent, or Firm* — Knobbe Martens Olson & Bear LLP

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(22) Filed: **Mar. 22, 2016**

(57) **CLAIM**

(30) **Foreign Application Priority Data**

The ornamental design for a gas flow control plate for a semiconductor manufacturing apparatus, as shown and described.

Jan. 8, 2016 (KR) 30-2016-0000957

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

DESCRIPTION

(58) **Field of Classification Search**

USPC D13/182; D15/144, 144.2; D23/259, D23/260, 261, 262, 263, 264, 265, 233, D23/209, 235

CPC .. H01J 37/32642; H01J 37/32; H01J 37/3244; H01J 37/32449; H01J 37/32623; H01J 37/32633; C30B 25/14; C30B 25/16; C30B 25/165; C23C 16/00; C23C 16/4412; C23C 16/455; C23C 16/45563; C23C 16/45574; C23C 16/4558; C23C 16/45565; C23C 16/44; C23C 16/4401; C23C 16/4402; C23C 16/4404; C23C 16/4408; C23C 16/45517; C23C 16/45519; C23C 16/45521; C23C 16/45559; C23C 16/45568; C23C 16/4557; C23C 16/45587; C23C 16/458; H01L 21/67; H01L 21/67011; H01L 21/67063; H01L 21/67069; H01L

FIG. 1 is a perspective view of a gas flow control plate for a semiconductor manufacturing apparatus showing our new design;

FIG. 2 is a front elevational view thereof;

FIG. 3 is a rear elevational view thereof;

FIG. 4 is a left side elevational view thereof;

FIG. 5 is a right side elevational view thereof;

FIG. 6 is a top plan view thereof;

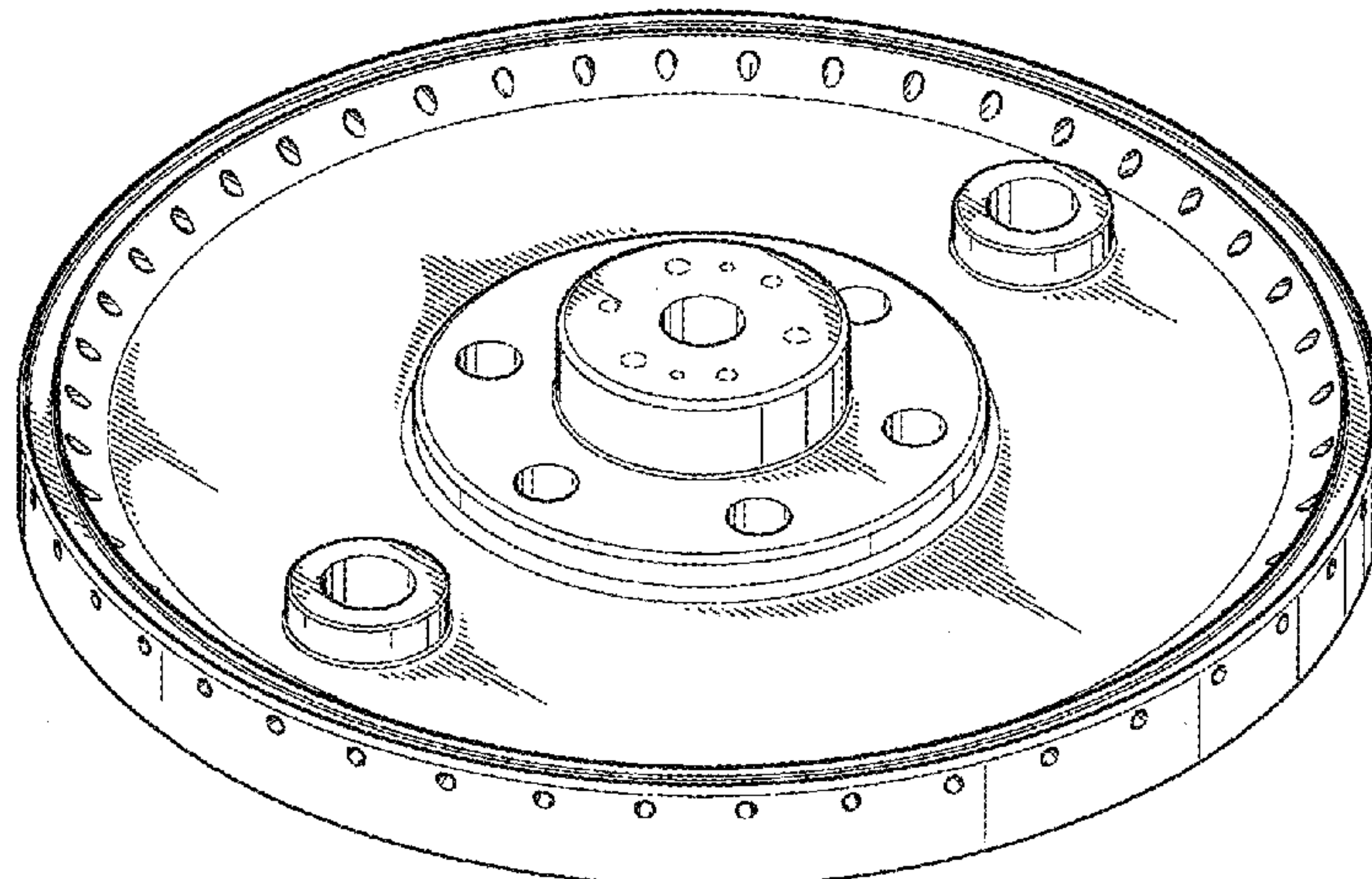
FIG. 7 is a bottom plan view thereof;

FIG. 8 is a cross sectional perspective view taken along line 8-8 of FIG. 6; and,

FIG. 9 is a cross sectional view taken along line 9-9 of FIG. 6.

The broken lines shown in the drawings represent portions of the gas flow control plate for a semiconductor manufacturing apparatus, that form no part of the claimed design.

1 Claim, 6 Drawing Sheets



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FIG. 1

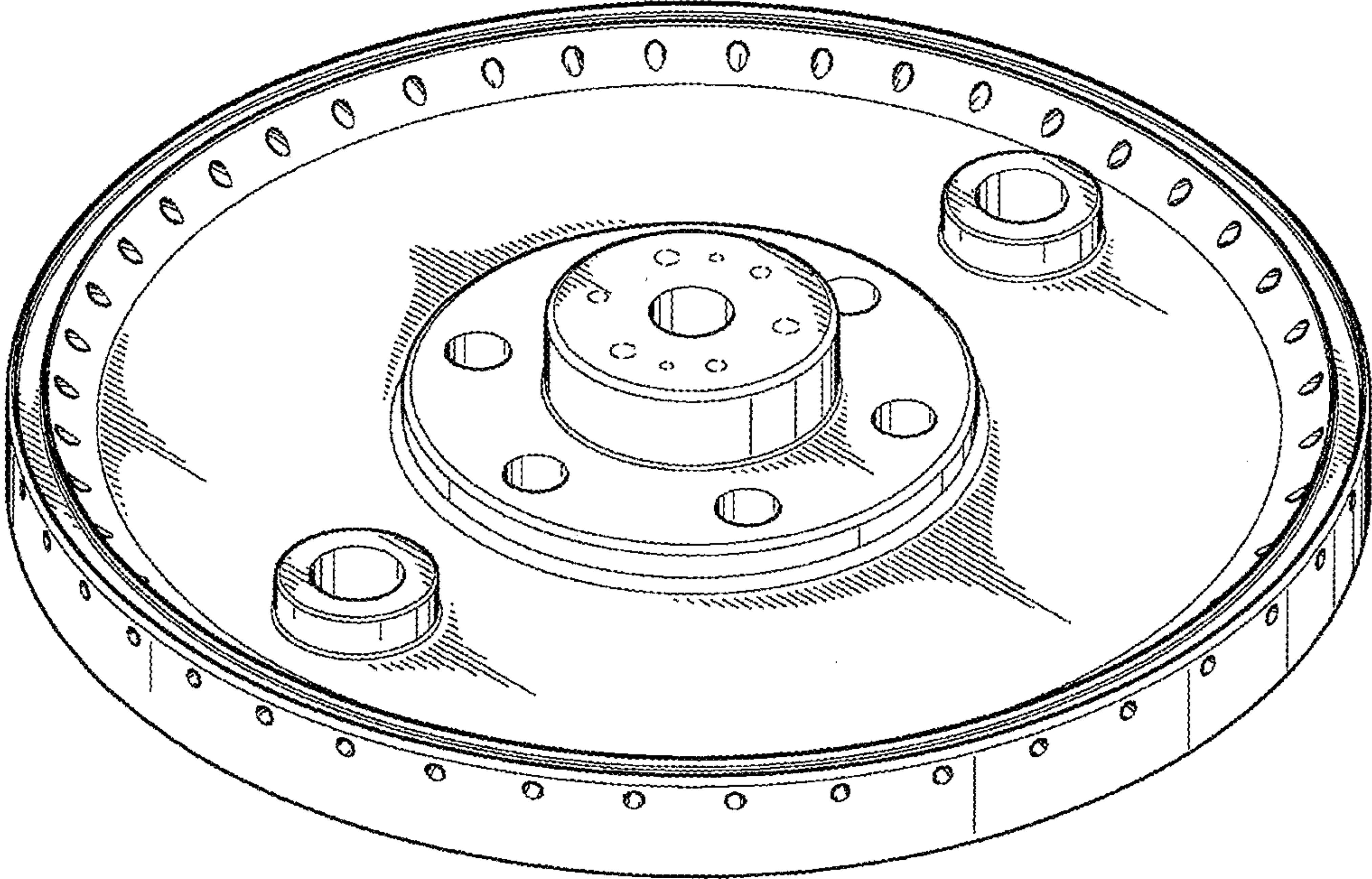


FIG. 2

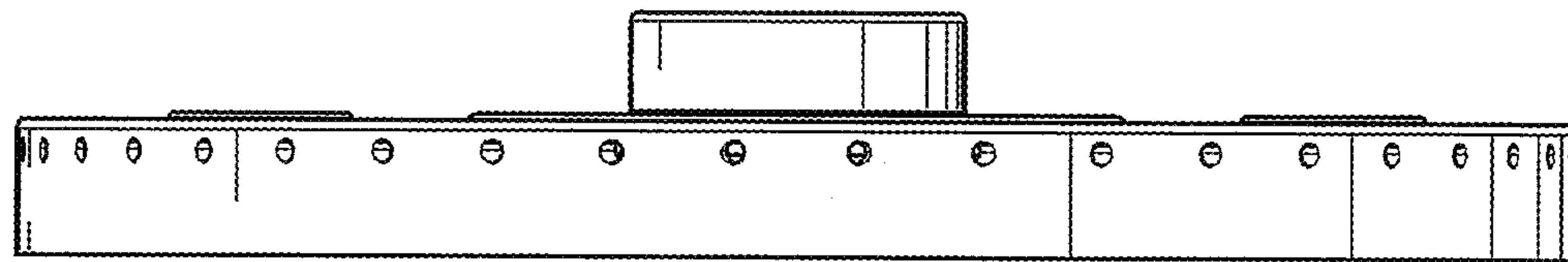


FIG. 3

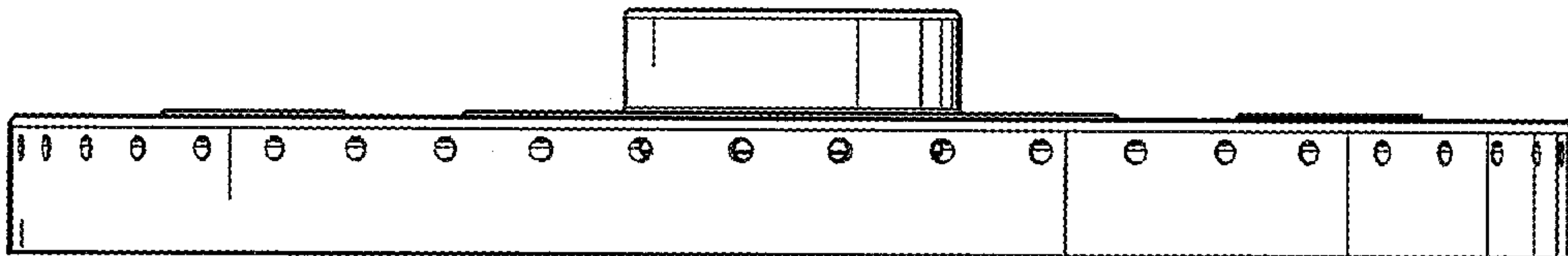


FIG. 4

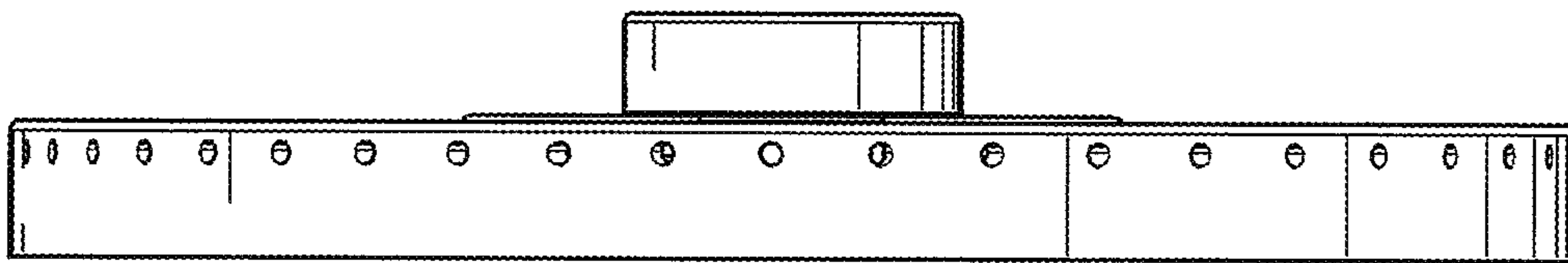


FIG. 5

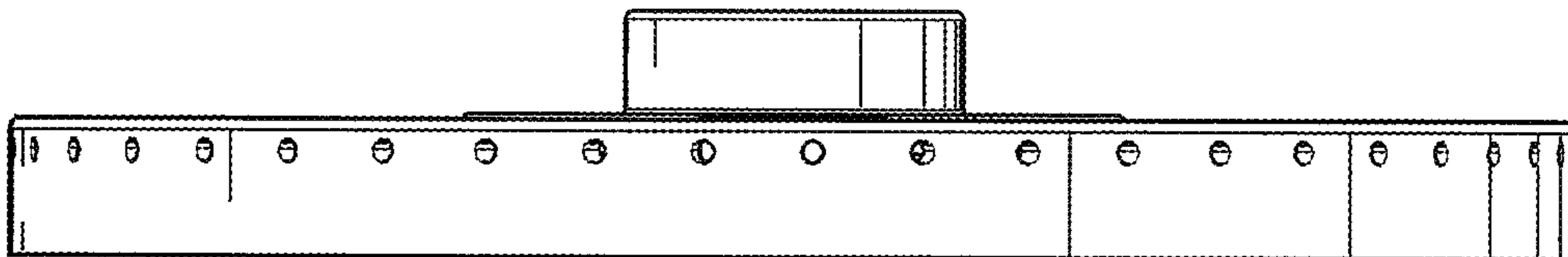


FIG. 6

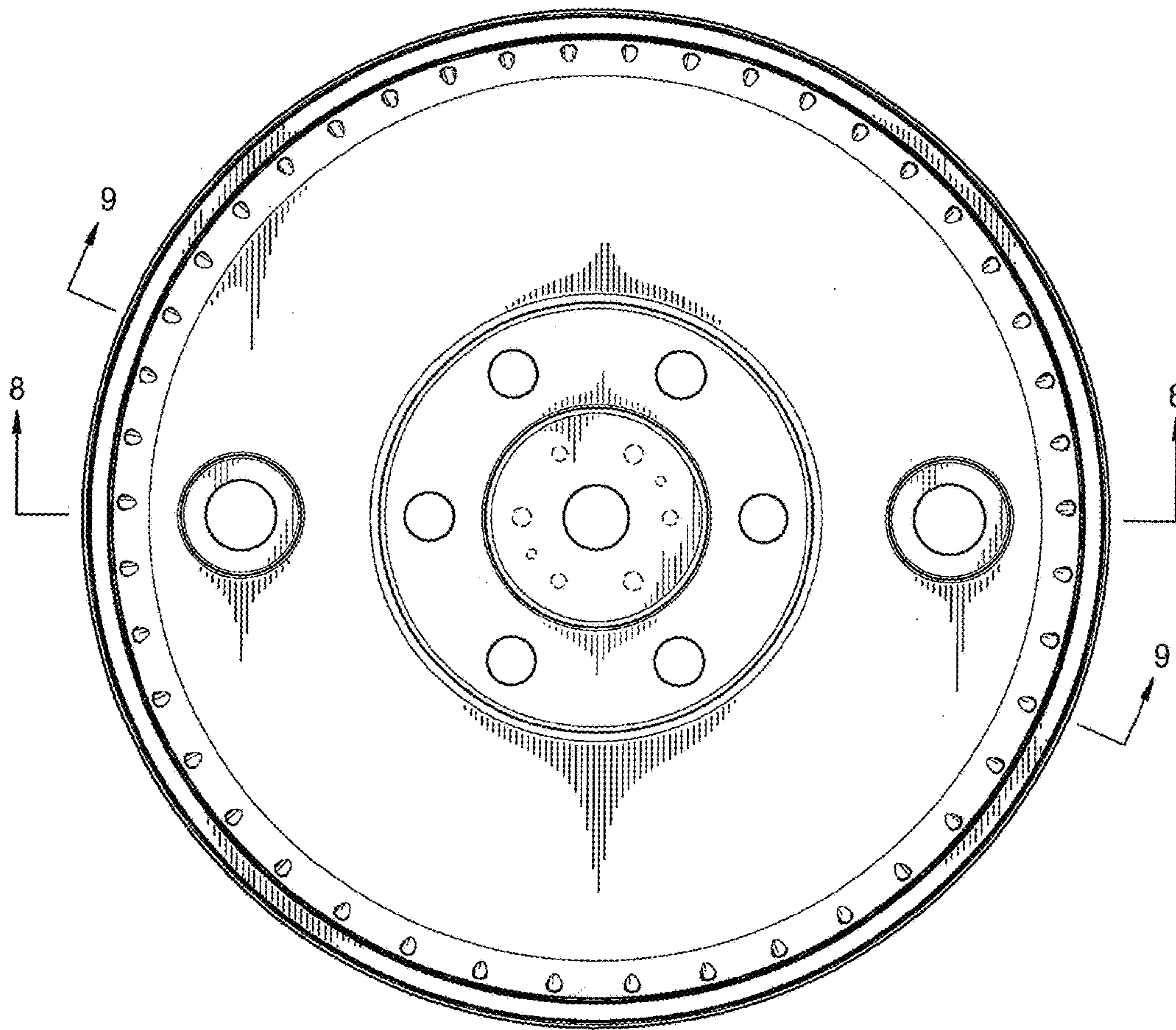


FIG. 7

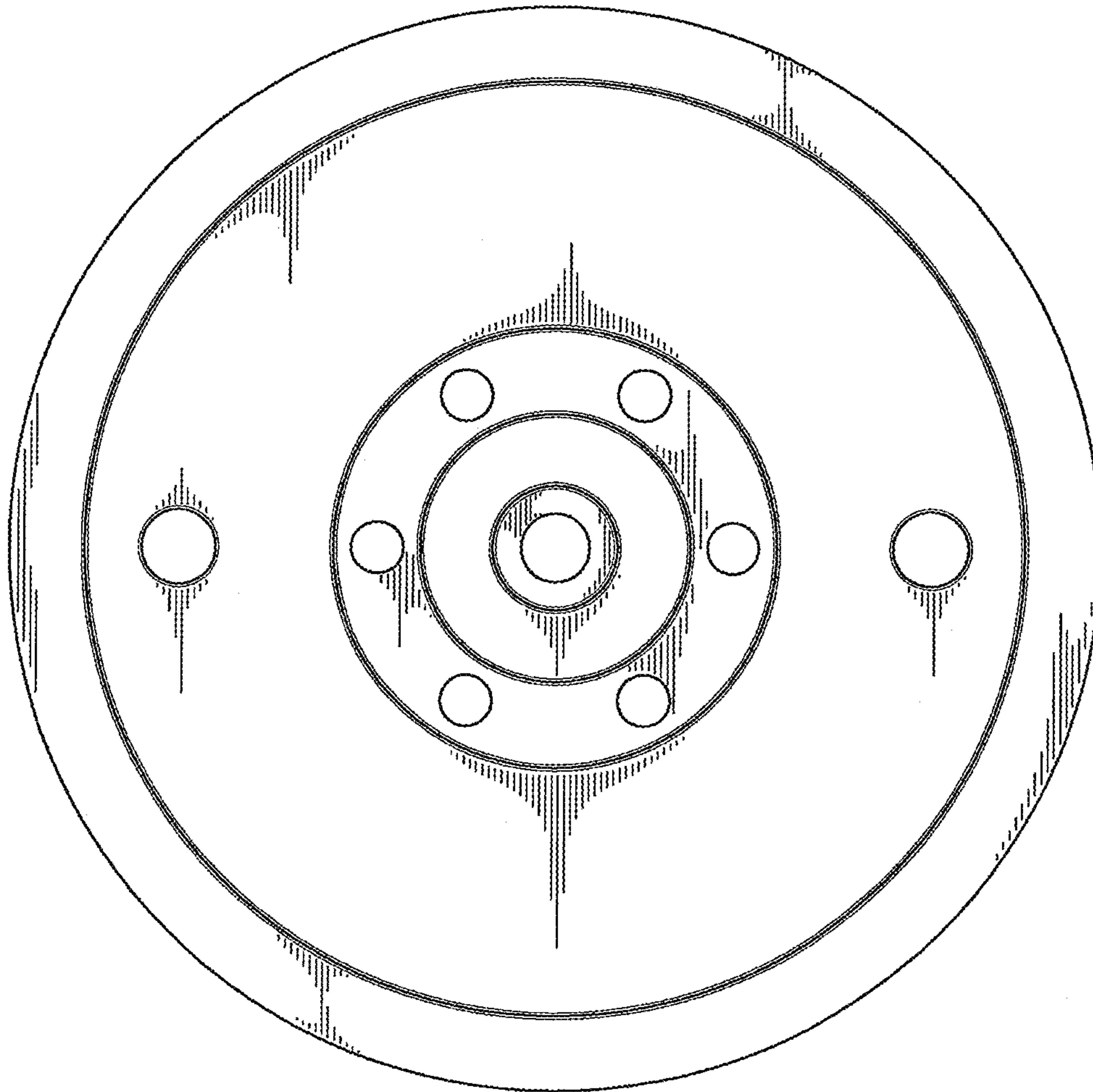


FIG. 8

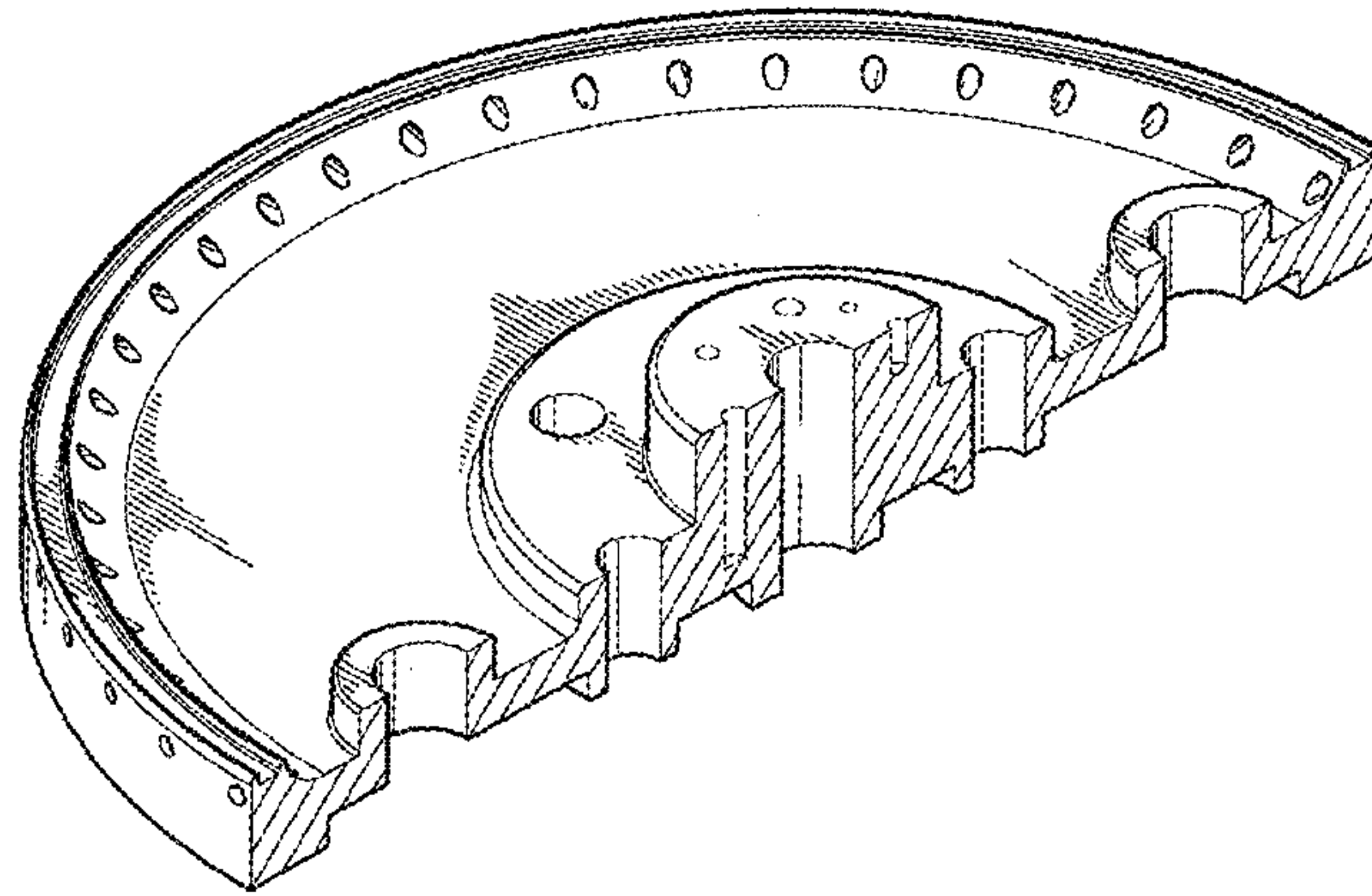


FIG. 9

